

L6	1	semiconductor and (strong adj bond\$5) and (weak adj bond\$5) and electrode and (actuatable adj element) and @ad<="20010912"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/27 13:41
L7	1	("20040201013").PN.	US-PGPUB; USPAT	OR	OFF	2005/04/27 13:58
L8	1	semiconductor and (strong adj bond\$5) and (weak adj bond\$5) and electrode and ((actuatable adj element) or ((contact or interconnect) adj (electric\$6 adj control))) and @ad<="20010912"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/27 13:44
L11	1	("6309945").PN.	US-PGPUB; USPAT	OR	OFF	2005/04/27 13:58
S3	542	(438/40).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/14 12:32
S4	1	("6309945").PN.	US-PGPUB; USPAT	OR	OFF	2005/04/27 13:21
S7	289	257/51.ccls. and @ad<="20010518"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/18 09:33
S8	147	(438/82).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/18 09:33
S9	329	(257/51).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/18 09:33
S10	788	438/99,40,82.ccls. and @ad<="20010518"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/27 13:35

S11	499	(438/99).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/18 09:34
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